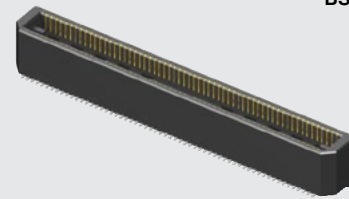


BTE-040-02-L-D-A



BTE-060-02-F-D-A

BSE-020-01-F-D-A



**BTE, BSE SERIES**

**(0.80 mm) .0315"**

# BASIC BLADE & BEAM HEADER & SOCKET

## SPECIFICATIONS

For complete specifications and recommended PCB layouts see [www.samtec.com?BTE](http://www.samtec.com?BTE) or [www.samtec.com?BSE](http://www.samtec.com?BSE)

- Insulator Material:** Liquid Crystal Polymer
- Contact Material:** Phosphor Bronze
- Plating:** Au or Sn over 50 μ" (1.27 μm) Ni
- Current Rating:** 2 A per pin (2 pins powered)
- Operating Temp Range:** -55 °C to +125 °C
- Voltage Rating:** 225 VAC with 5 mm Stack Height
- Max Cycles:** 100
- RoHS Compliant:** Yes

## PROCESSING

- Lead-Free Solderable:** Yes
- SMT Lead Coplanarity:** (0.10 mm) .004" max (020-080) (0.15 mm) .006" max (100-120)\*
- \*(.004" stencil solution may be available; contact [IPG@samtec.com](mailto:IPG@samtec.com))
- Board Stacking:** For applications requiring more than two connectors per board or 80 positions or higher, contact [ipg@samtec.com](mailto:ipg@samtec.com)

## RECOGNITIONS

For complete scope of recognitions see [www.samtec.com/quality](http://www.samtec.com/quality)



## ALSO AVAILABLE (MOQ Required)

- 30 μ" (0.76 μm) Gold
- Edge Mount Capability
- Friction Lock option
- 11 mm, 14 mm, 16.10 mm, 19.10 mm, 22 mm, 25 mm and 30 mm Stack Height (Caution: Some automatic placement/inspection machines may have component height restrictions. Please consult machinery specifications.)

**Note:** Some lengths, styles and options are non-standard, non-returnable.

<b>BTE</b>	<b>NO. OF POSITIONS PER ROW</b>	<b>LEAD STYLE</b>	<b>PLATING OPTION</b>	<b>D</b>	<b>A</b>	<b>OTHER OPTION</b>						
Mates with: BSE		Specify LEAD STYLE from chart	-F = Gold Flash on contact, Matte Tin on tail			-K = (7.00 mm) .275" DIA Polyimide Film Pick & Place Pad						
-020, -040, -060, -080, -100, -120			-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail			-TR = Tape & Reel (80 positions maximum)						
		<table border="1"> <tr> <th>LEAD STYLE</th> <th>A</th> </tr> <tr> <td>-01</td> <td>(4.27) .168</td> </tr> <tr> <td>-02</td> <td>(7.21) .284</td> </tr> </table>	LEAD STYLE	A	-01	(4.27) .168	-02	(7.21) .284	-C* = Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails			<b>POWER/SIGNAL APPLICATION</b> 
LEAD STYLE	A											
-01	(4.27) .168											
-02	(7.21) .284											
<b>MATED HEIGHT</b> <table border="1"> <thead> <tr> <th>LEAD STYLE</th> <th>MATED HEIGHT*</th> </tr> </thead> <tbody> <tr> <td>-01</td> <td>(5.00) .197</td> </tr> <tr> <td>-02</td> <td>(8.00) .315</td> </tr> </tbody> </table> <p>*Processing conditions will affect mated height.</p>		LEAD STYLE	MATED HEIGHT*	-01	(5.00) .197	-02	(8.00) .315				<p>*Note: -C Plating passes 10 year MFG testing</p>	
LEAD STYLE	MATED HEIGHT*											
-01	(5.00) .197											
-02	(8.00) .315											



<b>BSE</b>	<b>NO. OF POSITIONS PER ROW</b>	<b>01</b>	<b>PLATING OPTION</b>	<b>D</b>	<b>A</b>	<b>OTHER OPTION</b>
Mates with: BTE			-F = Gold Flash on contact, Matte Tin on tail			-TR = Tape & Reel (80 positions maximum)
-020, -040, -060, -080, -100, -120			-L = 10 μ" (0.25 μm) Gold on contact, Matte Tin on tail			
			-C* = Electro-Polished Selective 50 μ" (1.27 μm) min Au over 150 μ" (3.81 μm) Ni on Signal Pins in contact area, Matte Tin over 50 μ" (1.27 μm) min Ni on all solder tails			<p>*Note: -C Plating passes 10 year MFG testing</p>

Due to technical progress, all designs, specifications and components are subject to change without notice.

[WWW.SAMTEC.COM](http://WWW.SAMTEC.COM)

All parts within this catalog are built to Samtec's specifications. Customer specific requirements must be approved by Samtec and identified in a Samtec customer-specific drawing to apply.